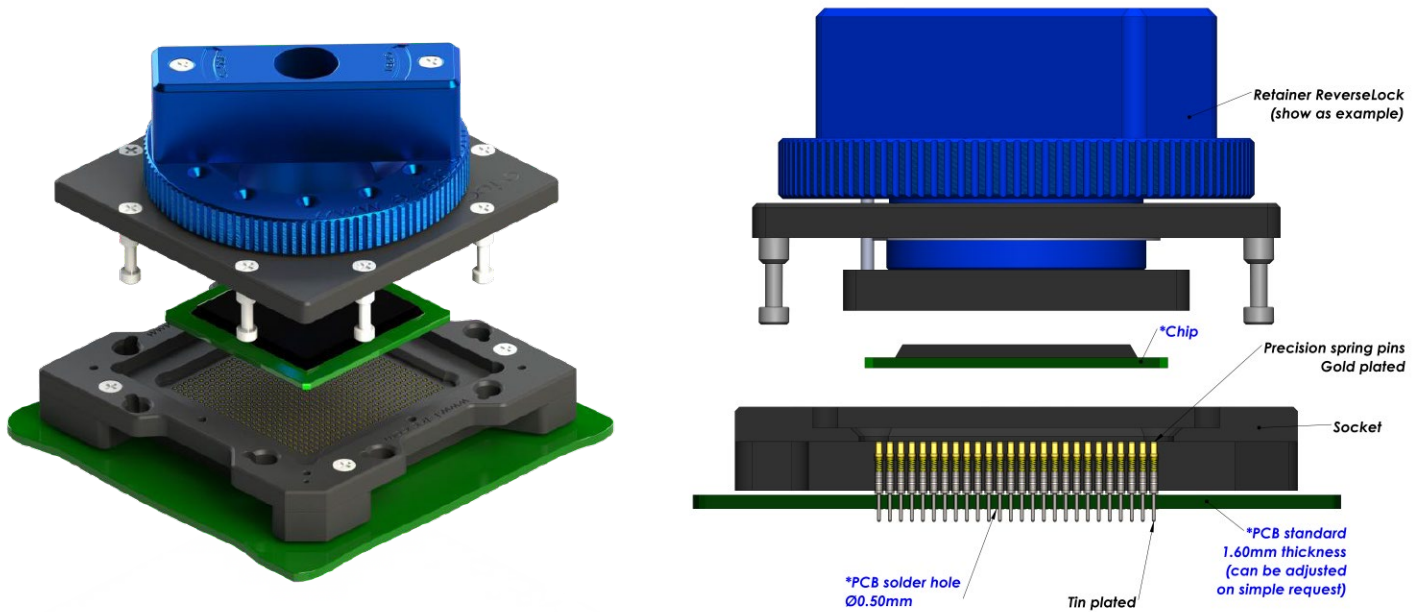


# Through-hole (THT) soldering Test Socket

For LGA / QFN / MLF / MLP / LCC Package

1.00 mm pitch (from 1.00 mm up to 1.26 mm)



## E-tec Interconnect AG is the world leading Test socket manufacturer

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 1070			
Application	Through-hole technology	Force	25 gr
Mounting	THT	Current rating	1.8 A
Bandwidth (GHz@-1dB)	3.4 GHz	Capacitance pF	1.03 pF
Contact resistance	<100mOhm	Inductance nH	1.80 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	Through-hole	Mating cycles	100 K

## How to order

**LP # #### -107# - ##### #5 #**

<p><b>Shape of tip</b></p> <p>P : Pointed</p> <p><b>Options:</b></p> <p>C : Crown</p>	<p><b>Nbr of contacts</b></p> <p>Depends on ballcount of chip</p>	<p><b>Contact type</b></p> <p>70 : Standard THT</p> <p>72 : Special THT to plug into MGS adapters</p>	<p><b>Plating</b></p> <p>95: Tin / Gold</p> <p>55: Gold/ Gold</p> <p>Other on request</p>	<p><b>Option code</b> (see page 16-19)</p> <p>D : Dead bug</p> <p>M : Multi frames</p> <p>U : Multi packages</p> <p>C : Converter plate</p> <p>S : Custom opening slot</p> <p>L : Locating pegs</p> <p>A : Alignment plate</p> <p>H : Heatsink</p> <p>F : Fan + Heatsink</p> <p>P : Thermal drain pad</p> <p>W : Transparent lid</p> <p>I : Steel retention lid</p> <p>B : Aluminium retention lid</p> <p>T : Torque tool fixture</p> <p>G : Handling button</p>
<p><b>Retention frame type (Lid)</b> (see page 12-15)</p> <p>W: TwistLock</p> <p>F: FastLock</p> <p>B: SpringLock</p> <p>H: Open Clamshell Alu (&lt;200 contacts)</p> <p>J: Clamshell Alu (&gt;200 contacts)</p> <p>L: Open Lever Clamshell Alu (&gt;200 contacts)</p> <p>S: ScrewLock</p> <p>Q: Open QuickLock (&lt;200 contacts)</p> <p>D: QuickLock (&gt;200 contacts)</p> <p>M: Injection Molded ClamShell</p> <p>R: ReverseLock</p> <p>T: SlimLock</p>		<p><b>Grid code / Config. code</b></p> <p>Will be given by the factory after receipt of the chip datasheet</p>		